

## NCE P-Channel Enhancement Mode Power MOSFET

### **Description**

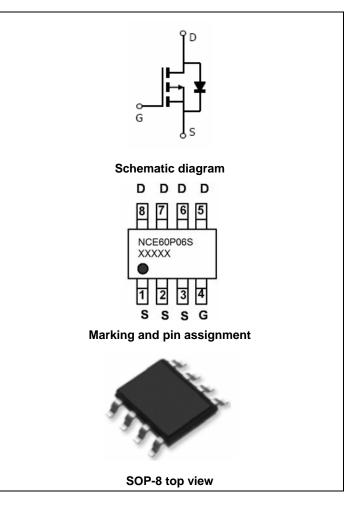
The NCE60P06S uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

#### **General Features**

- $V_{DS}$  =-60V, $I_{D}$  =-6A  $R_{DS(ON)}$  <45m $\Omega$  @  $V_{GS}$ =-10V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

#### **Application**

- Power switching application
- Hard switched and high frequency circuits
- DC-DC Converter



## **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE60P06S	NCE60P06S	SOP-8	Ø330mm	12mm	4000 units

#### Absolute Maximum Ratings (T<sub>A</sub>=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	-60	V		
Gate-Source Voltage	V <sub>G</sub> s	±20	V		
Drain Current-Continuous	I <sub>D</sub>	-6	А		
Drain Current-Continuous(T <sub>C</sub> =100 °C)	I <sub>D</sub> (100℃)	-4.2	Α		
Pulsed Drain Current	I <sub>DM</sub>	-30	А		
Maximum Power Dissipation	P <sub>D</sub>	3	W		
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 150	$^{\circ}$		

#### **Thermal Characteristic**

Thermal Resistance ,Junction-to-Ambient (Note 2)	$R_{ hetaJA}$	42	°C/W

## **Electrical Characteristics (T<sub>A</sub>=25 ℃ unless otherwise noted)**

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-60	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-60V,V <sub>GS</sub> =0V	-	-	1	μΑ
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)			•			
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_{D}=-250\mu A$	-1.5	-2.6	-3.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	$V_{GS}$ =-10V, $I_D$ =-5A	-	40	45	mΩ
Forward Transconductance	<b>g</b> FS	$V_{DS}$ =-5 $V$ , $I_{D}$ =-5 $A$	-	16	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C <sub>lss</sub>	\/ - 20\/\/ -0\/	-	2578	-	PF
Output Capacitance	Coss	V <sub>DS</sub> =-30V,V <sub>GS</sub> =0V, F=1.0MHz  - 2578  - 112  - 102		112	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	r-1.0ivinz	-	102	-	PF
Switching Characteristics (Note 4)			•			
Turn-on Delay Time	t <sub>d(on)</sub>		-	10	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =-30 $V$ , , $R_L$ =30 $\Omega$	-	6	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =-10 $V$ , $R_{GEN}$ =6 $\Omega$	-	44	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	13	-	nS
Total Gate Charge	Qg	\/ - 20\/ I - EA	-	46.2	-	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =-30V, $I_{D}$ =-5A, $V_{GS}$ =-10V	-	8.6	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	VGS10V	-	10.4	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-6A	-	-	-1.2	V
Diode Forward Current (Note 2)	Is		-	-	-6	Α

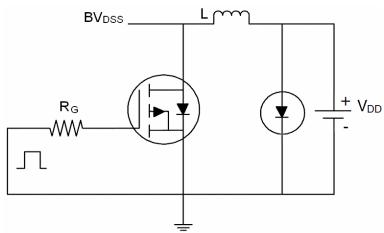
#### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

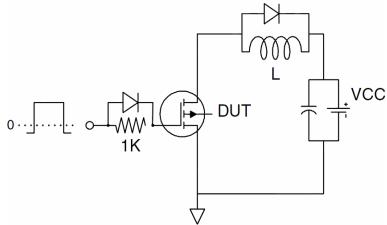


## **Test Circuit**

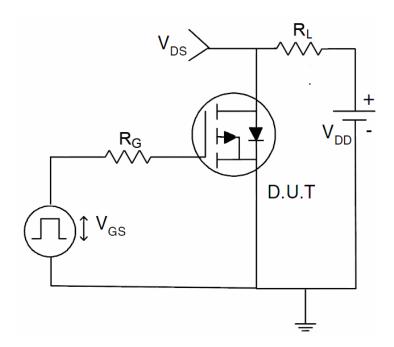
# 1) E<sub>AS</sub> Test Circuit



# 2) Gate Charge Test Circuit

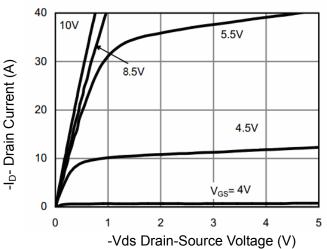


## 3) Switch Time Test Circuit

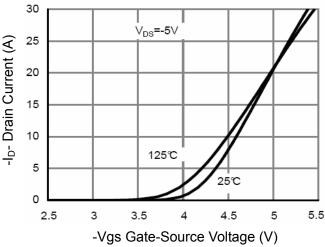




## **Typical Electrical and Thermal Characteristics**



**Figure 1 Output Characteristics** 



**Figure 2 Transfer Characteristics** 

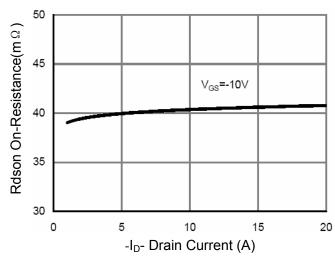
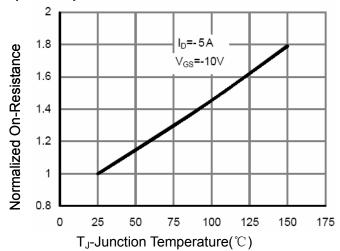


Figure 3 Rdson- Drain Current

## (Curves)



**Figure 4 Rdson-Junction Temperature** 

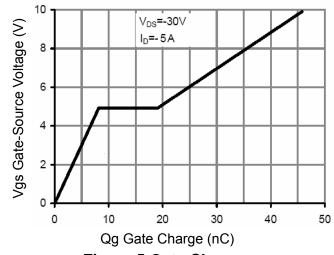


Figure 5 Gate Charge

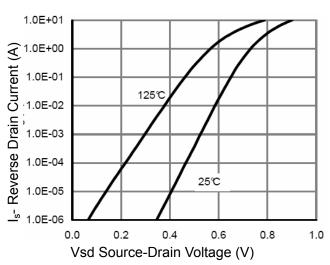


Figure 6 Source- Drain Diode Forward



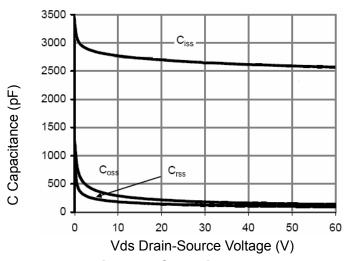
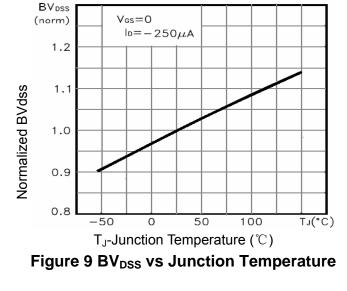
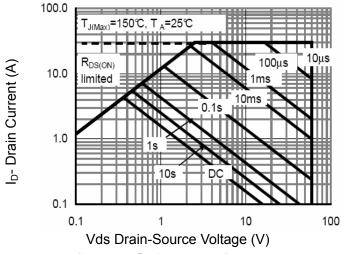


Figure 7 Capacitance vs Vds





**Figure 8 Safe Operation Area** 

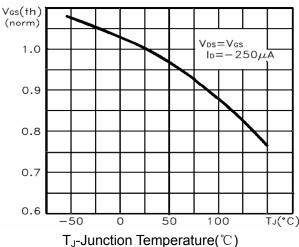


Figure 10 V<sub>GS(th)</sub> vs Junction Temperature

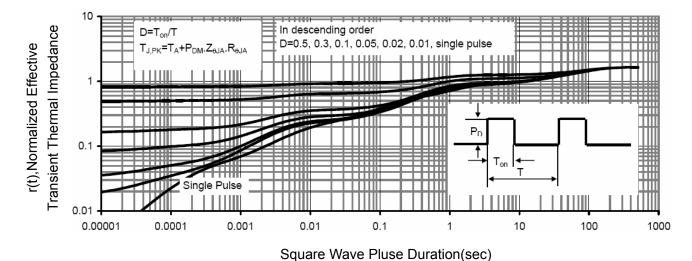
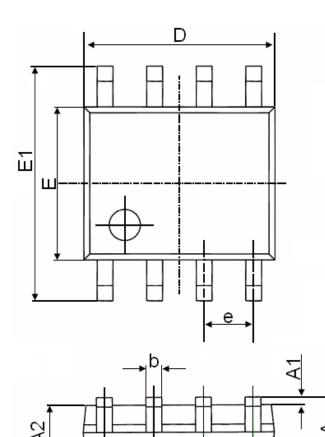
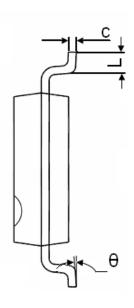


Figure 11 Normalized Maximum Transient Thermal Impedance



# **SOP-8 Package Information**





Symbol	Dimensions I	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270(BSC)		0.050	(BSC)	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	



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